



Product Change Notification - RMES-18SSPJ335

Date:

08 Aug 2019

Product Category:**Notification subject:**

CCB 3862 Final Notice: Implement Microchip top marking changes for selected Microsemi CBU products.

Notification text:**PCN Status:**

Final notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

Note 1: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Note 2: As part of the integration process additional products may be identified that were not part of the original list.

Description of Change:

Implement Microchip top marking changes for selected Microsemi products within the Microsemi subsidiaries Microsemi Solutions Sdn. Bhd. which includes formerly Communications Business Unit (CBU) products.

Pre Change:

Microsemi top marking format and traceability code

Post Change:

Microchip top marking format and traceability code

Pre and Post Change Summary:

	PRE CHANGE (Microsemi)	POST CHANGE (Microchip)
Top mark	Microsemi top marking format and traceability code	Microchip top marking format and traceability code
See attached pre and post marking guidelines		

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve manufacturability and traceability by standardizing marking format for selected Microsemi products as part of the integration of Microchip and Microsemi.

Change Implementation Status:

In Progress

Earliest Implementation Date:

November 1, 2019



Note: The earliest implementation date is the earliest date that we may implement any combination of the changes listed in this PCN as we will not implement any of the proposed changes prior to this date. After the earliest implementation date these changes may occur to any product over the course of many months depending on inventory levels and business conditions.

Time Table Summary:

	August 2019					->	November 2019				
Workweek	31	32	33	34	35		44	45	46	47	48
Final PCN Issue Date		X									
Estimated Implementation Date							X				

Method to Identify Change:

Traceability, top marking

Contact Microchip:

You may contact your local [Microchip Sales and Distribution](#). Contact information is also provided on the attached Frequently Asked Questions (FAQ).

If applicable, please also copy your local Microchip field sales and/or field quality representative.

Qualification Report:

Not Applicable

Revision History:

August 08, 2019: Issued final notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN_RMES-18SSPJ335_Affected_CPN.pdf](#)

[Frequently Asked Questions Microsemi November.pdf](#)

[Pre and Post Changes Marking guidelines for PCN_RMES-18SSPJ335.pdf](#)

[PCN_RMES-18SSPJ335_Affected_CPN.xlsx](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to [receive Microchip PCNs via email](#) please register for our PCN email service at our [PCN home page](#) select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the [PCN FAQ](#) section.

If you wish to [change your PCN profile, including opt out](#), please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

RMES-18SSPJ335- CCB 3862 Final Notice: Implement Microchip top marking changes for selected Microsemi CBU products.

Affected Catalog Part Number (CPN)

PCN_RMES-18SSPJ335
CATALOG_PART_NBR
PAS6413A-F3GC
WP441W6A1-500-NFEI
WP32C0W5NHEI-450B2
WP3061W8NHEI-250B1
WP3232M5NELI-320B2
WIN847M6NHLI-250A1
WP441R6A1-500-EFEI
PAS5211A-F3EI
WP34C2R4EFEI-400B2
WIN2A2EHEI-300A1
WP3232M6NFEI-320B2
WP32C2M6NELI-450B2
PAS7400B-NGI
WIN840W6NHEI-300A1
PAS6512B-F3GI
PAS5201-A0
WP32C2W3EFEI-320B2
WIN860M6NHEI-300A1
WP32C2W6NFEI-400B2
WP441R6A1-500-NFEI
WP441W6A1-500-EFEI
PAS5201-L0
PAS6401B-F3GI
PAS6511B-F3GI
WP33C2A1EFEI-450B2
WP32C2A4EFEI-400B2
PAS7401B-PGI
WP3160W6NFEI-320B1
WP3161W6NFEI-320B1
WP441W6A1-400-EFEI
WP3161W1EFEI-320B1
PAS6511B-F3EI
WP32C2M6NHEI-400B2
WP3160W3NFEI-320B1
WIN2A3NHEI-250A1-2
WIN2A3NHEI-250A1
WP3392D4NFEI-320B2
WP3232M5NHEI-320B2
WP3161W6NHEI-400B1
WP34C2R4NFEI-400B2
WP3061W1NHEI-250B1
WP3161R4NFEI-320B1
WP3362D4NFEI-320B2
WP441W6A1-400-NFEI
WIN867R4NHEI-330A1

RMES-18SSPJ335- CCB 3862 Final Notice: Implement Microchip top marking changes for selected Microsemi CBU products.



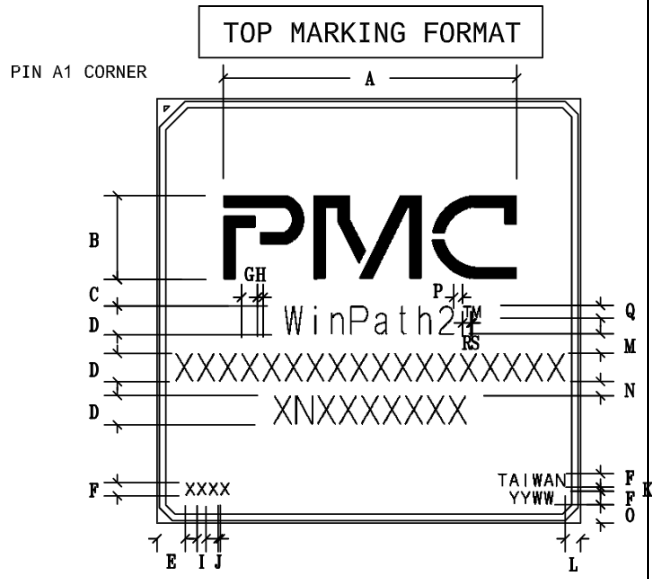
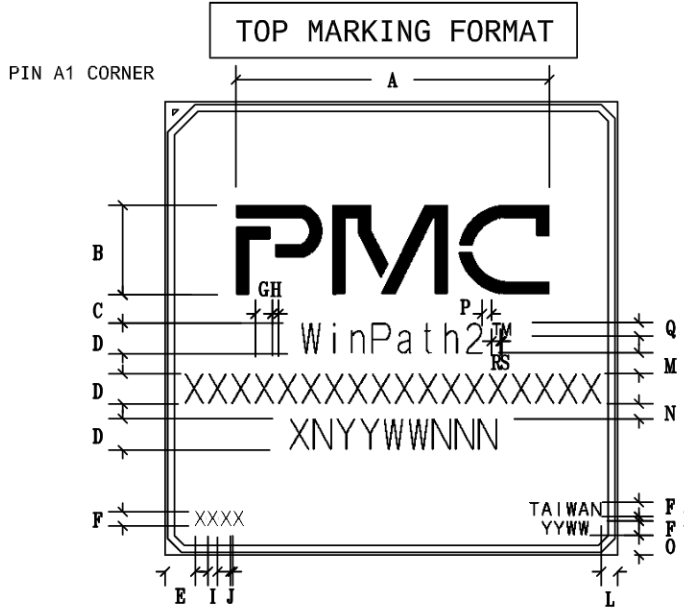
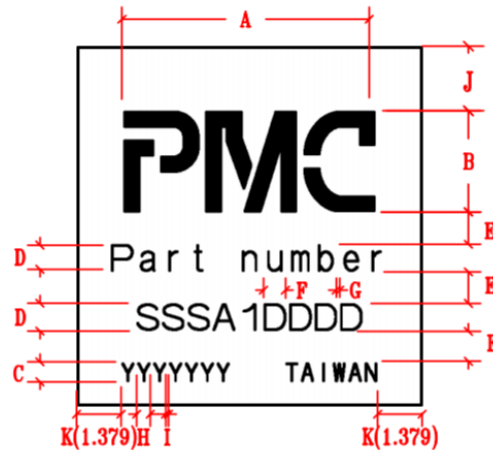
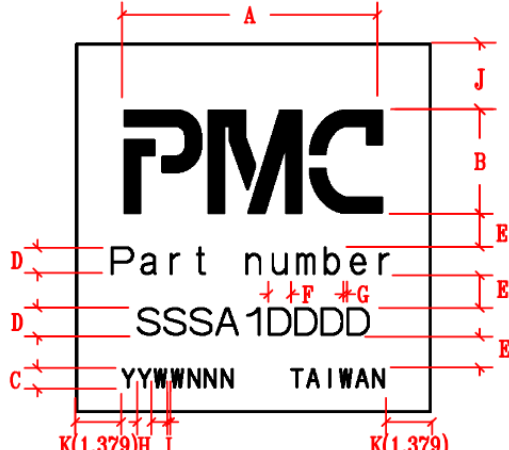
Affected Catalog Part Number (CPN)

PCN_RMES-18SSPJ335
CATALOG_PART_NBR
PAS6411B-F3GI
WIN860M6NHEI-350A1
WP34C2R6EFEI450B2R
WIN847W6NHEI-250A1
WP33C2D4NFEI-450B2
WIN867M6NHEI-300A1
WP34C2R6NFEI450B2R
WIN847W3NHEI-250A1
WP3161F5NFEI-320B1
WP3061W2NHEI-250B1
WP32C2M6NELI-400B2
WP3161D4NFEI-400B1
WP3161EFEI-400B1

PART MARKING GUIDELINE (Supplement to PCN# RMES-18SSPJ335)

This chart is to be used as a general guidelines only and does not include custom marking. It does not contain actual part marking on any specific product.



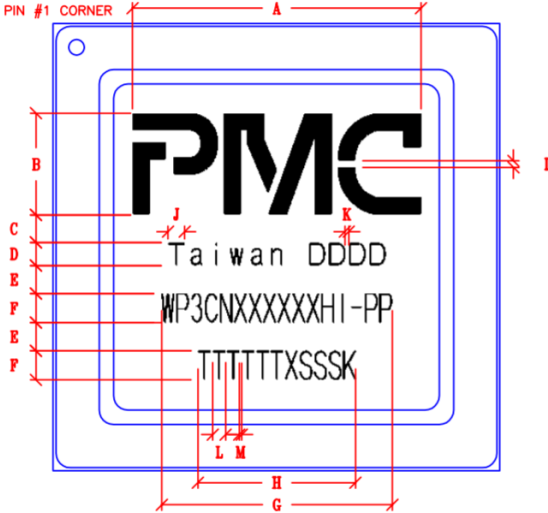
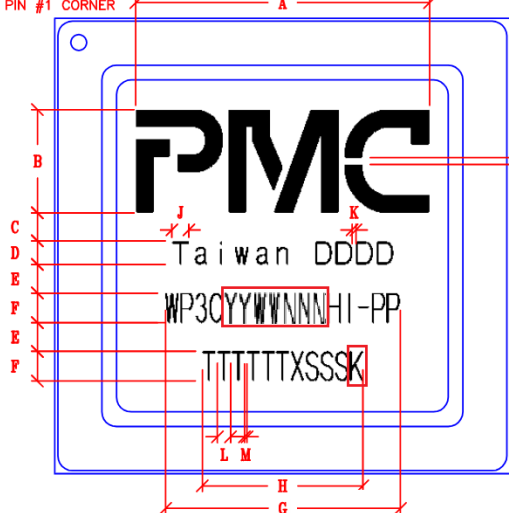
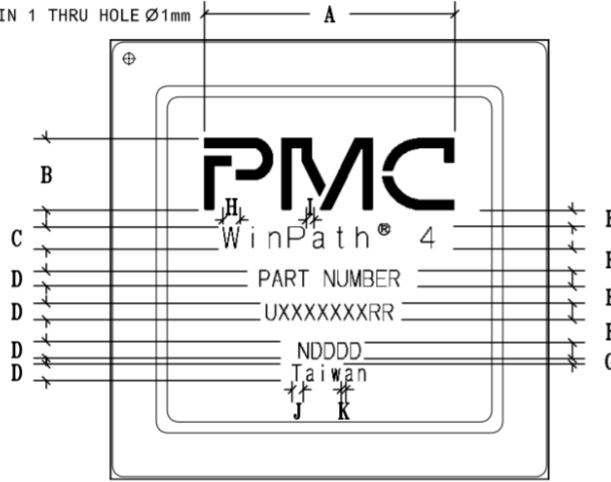
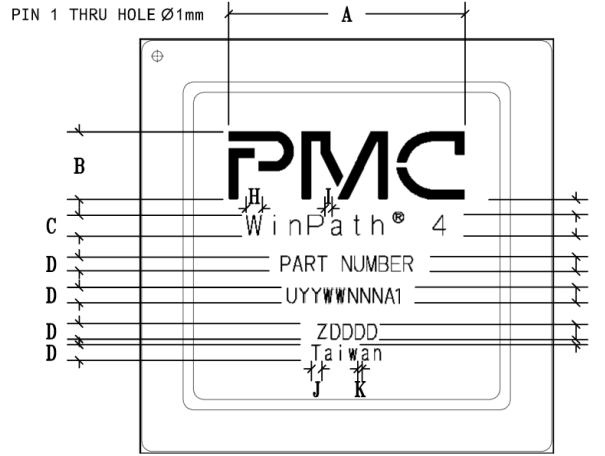
Note: X represents any number of characters that may change depending on to part ordered.

				
Product Family Name	Pre-Change Marking Diagram (MSCC) Microsemi	Pre-Change Marking Guidelines (MSCC) Microsemi	Post-Change Marking Diagram (MCHP) Microchip	Post-Change Marking Guidelines (MCHP) Microchip
WinPath 2 (WP2)		<p>Top Mark</p> <p>Line 1 – PMC Logo</p> <p>Line 2 – Product Family Name</p> <p>Line 3 – Catalog Part Number</p> <p>Line 4- XNXXXXXXXX = MSCC Lot #</p> <p>Bottom left corner = Assembly Code</p> <p>Bottom right corner = Country of Origin and duplicated assembly date code</p> <p>● = Pin 1 location</p>		<p>Top Mark</p> <p>Line 1 – PMC Logo</p> <p>Line 2 – Product Family Name</p> <p>Line 3 - Catalog Part Number</p> <p>Line 4- XNYYWWNNN= MCHP Trace code</p> <p>Bottom left corner = Hard coded random characters</p> <p>Bottom right corner = Country of Origin and assembly date code</p> <p>● = Pin 1 location</p>
WinPath 2L (WP2L)		<p>Top Mark</p> <p>Line 1 – PMC Logo</p> <p>Line 2 – Catalog Part Number</p> <p>Line 3 – Speed, Revision and Assembler code</p> <p>Line 4 – YYYYYYYY – Lot code and Country of Origin</p> <p>● = Pin 1 location</p>		<p>Top Mark</p> <p>Line 1 – PMC Logo</p> <p>Line 2 - Catalog Part Number</p> <p>Line 3 – Speed, Revision and Assembler code</p> <p>Line 4 – YYWWNNN = MCHP Trace code and Country of Origin</p> <p>● = Pin 1 location</p>

PART MARKING GUIDELINE (Supplement to PCN# RMES-18SSPJ335)

This chart is to be used as a general guidelines only and does not include custom marking. It does not contain actual part marking on any specific product.



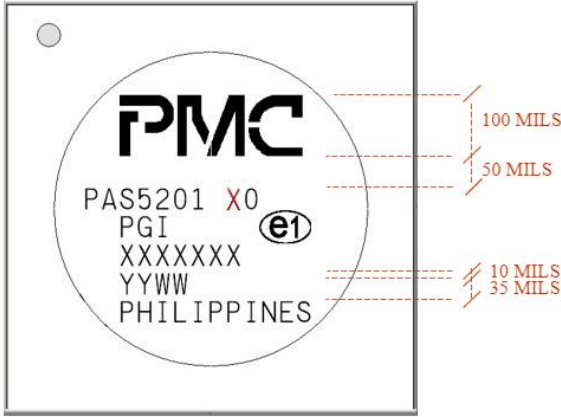
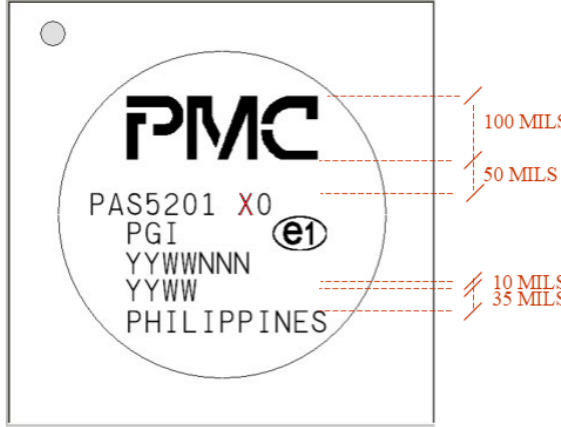
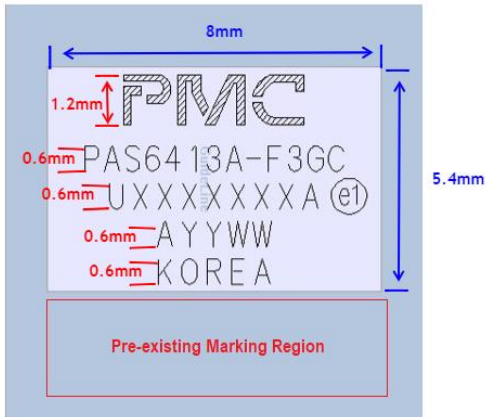
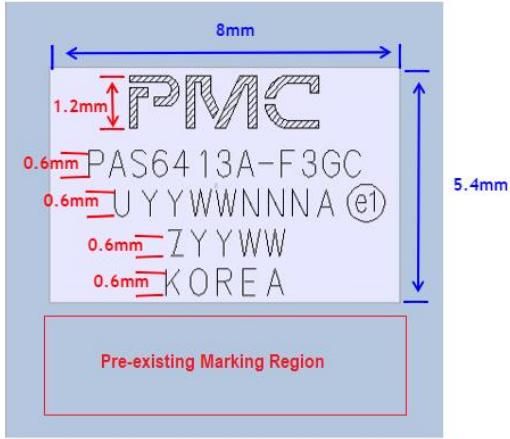
Note: X represents any number of characters that may change depending on to part ordered.

<div></div>			<div></div>	
Product Family Name	Pre-Change Marking Diagram (MSCC) Microsemi	Pre-Change Marking Guidelines (MSCC) Microsemi	Post-Change Marking Diagram (MCHP) Microchip	Post-Change Marking Guidelines (MCHP) Microchip
WinPath 3 & WinPath 3SL (WP3 & WP3SL)		<p>Top Mark</p> <p>Line 1 – PMC Logo</p> <p>Line 2 – Country of Origin and Assembler date code</p> <p>Line 3 - WP3CNXXXXXXHI-PP = Assembler code and MSCC Lot #</p> <p>Line 4- TTTTTXSSSK = Assembly Lot Number</p> <p>● = Pin 1 location</p>		<p>Top Mark</p> <p>Line 1 – PMC Logo</p> <p>Line 2 – Country of Origin and Assembler date code</p> <p>Line 3 - WP3CYYWWNNNHI-PP = WP3C = Catalog Part Numbers YYWWNNN = MCHP Trace code HI-PP = Catalog Part Numbers</p> <p>Line 4 TTTTTXSSSK = Assembly Lot Number</p> <p>● = Pin 1 location</p>
WinPath 4 (WP4)		<p>Top Mark</p> <p>Line 1 – PMC Logo</p> <p>Line 2 – Product Family Name</p> <p>Line 3 – Part Number</p> <p>Line 4 - UXXXXXXRR = Fab Code, MSCC Lot #, and Revision code</p> <p>Line 5 - NDDDD = Assembler code and date code</p> <p>● = Pin 1 location</p>		<p>Top Mark</p> <p>Line 1 – PMC Logo</p> <p>Line 2 – Product Family Name</p> <p>Line 3 – Part Number</p> <p>Line 4 - UYYWWNNNA1 = U – Hard coded random characters YYWWNNN – MCHP Trace code A1 – Hard coded random characters</p> <p>Line 5 ZDDDD = Z – Hard coded random characters DDDD - Assembler code and date code</p> <p>● = Pin 1 location</p>

PART MARKING GUIDELINE (Supplement to PCN# RMES-18SSPJ335)

This chart is to be used as a general guidelines only and does not include custom marking. It does not contain actual part marking on any specific product.



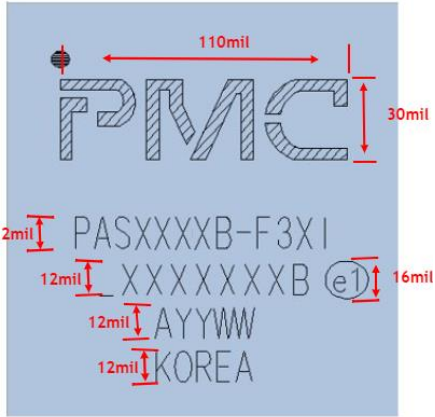
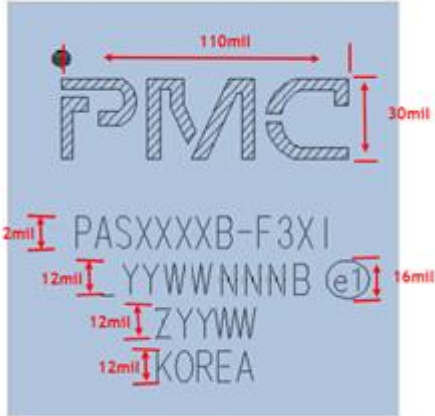
Note: X represents any number of characters that may change depending on to part ordered.

				
Product Family Name	Pre-Change Marking Diagram (MSCC) Microsemi	Pre-Change Marking Guidelines (MSCC) Microsemi	Post-Change Marking Diagram (MCHP) Microchip	Post-Change Marking Guidelines (MCHP) Microchip
PAS5201 (PAS5201A0 and PAS5201L0)		Top Mark Line 1 – PMC Logo Line 2 & Line 3– Catalog Part Number Line 4- XXXXXXXX = Lot code marking Line 5 – YYWW = Assembler date code Line 6 – Country of Origin ● = Pin 1 location		Top Mark Line 1 – PMC Logo Line 2 & Line 3– Catalog Part Number Line 4- YYWWNNN = MCHP trace code Line 5 – YYWW = Assembler date code Line 6 – Country of Origin ● = Pin 1 location
PAS6x13 (PAS6413 and PAS6513)		Top Mark Line 1 – PMC Logo Line 2 – Catalog Part Number Line 3 - UXXXXXXXXA = Lot code marking Line 4 – AYYWW = Assembler date code Line 5 – Country of Origin		Top Mark Line 1 – PMC Logo Line 2 – Catalog Part Number Line 3 - U = Hard coded random characters YYWWNNN = MCHP trace code A = Hard coded random characters Line 4 – Z = Hard coded random characters YYWW = Assembler date code Line 5 – Country of Origin

PART MARKING GUIDELINE (Supplement to PCN# RMES-18SSPJ335)

This chart is to be used as a general guidelines only and does not include custom marking. It does not contain actual part marking on any specific product.

Note: X represents any number of characters that may change depending on to part ordered.

				
Product Family Name	Pre-Change Marking Diagram (MSCC) Microsemi	Pre-Change Marking Guidelines (MSCC) Microsemi	Post-Change Marking Diagram (MCHP) Microchip	Post-Change Marking Guidelines (MCHP) Microchip
All other PAS devices		<p>Top Mark</p> <p>Line 1 – PMC Logo</p> <p>Line 2 – Catalog Part Number</p> <p>Line 3 - _XXXXXXB = Lot code marking</p> <p>“_” = Fab Code</p> <p>B = device revision</p> <p>Line 4 – AYYWW = Assembler date code</p> <p>Line 5 – Country of Origin</p> <p>● = Pin 1 location</p>		<p>Top Mark</p> <p>Line 1 – PMC Logo</p> <p>Line 2 – Catalog Part Number</p> <p>Line 3 - _YYWWNNNB = MCHP trace code</p> <p>“_” and B – Hard coded random characters</p> <p>Line 4 – Z = Hard coded random characters YYWW = Assembler date code</p> <p>Line 5 – Country of Origin</p> <p>● = Pin 1 location</p>